

MECHANICAL CASE OUTLINE

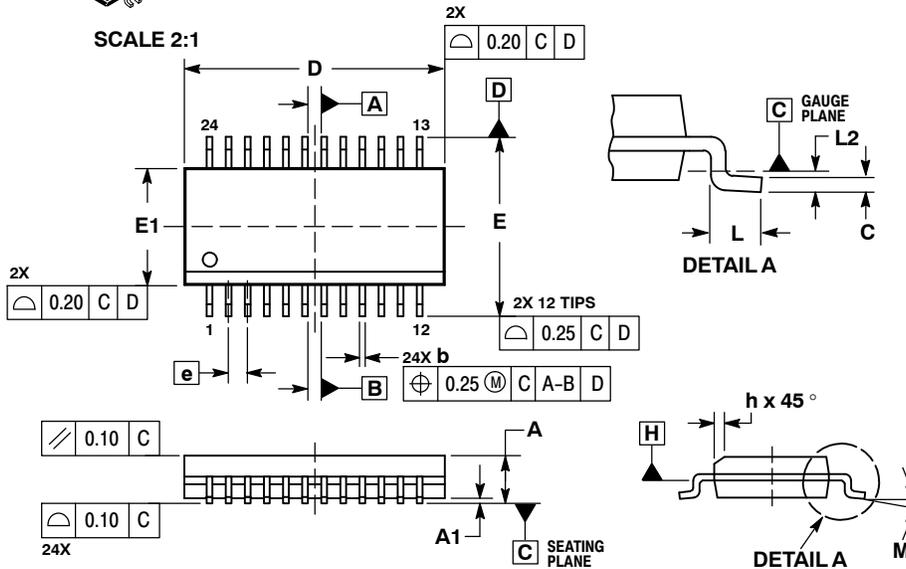
PACKAGE DIMENSIONS

ON Semiconductor®



QSOP24 NB CASE 492B-01 ISSUE A

DATE 06 MAY 2008

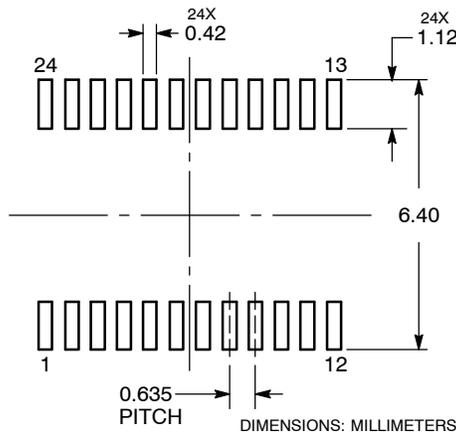


NOTES:

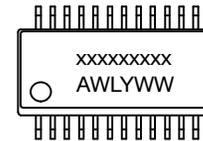
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION.
4. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.15 PER SIDE. D AND E1 ARE DETERMINED AT DATUM H.
5. DATUMS A AND B ARE DETERMINED AT DATUM H.

MILLIMETERS		
DIM	MIN	MAX
A	1.35	1.75
A1	0.10	0.25
b	0.20	0.30
C	0.19	0.25
D	8.65 BSC	
E	6.00 BSC	
E1	3.90 BSC	
e	0.635 BSC	
h	0.22	0.50
L	0.40	1.27
L2	0.25 BSC	
M	0°	8°

SOLDERING FOOTPRINT



GENERIC MARKING DIAGRAM*



- xxx = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

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NEW STANDARD:		
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